

Triple-cut form factor

2FF, 3FF, 4FF

Product overview

A secure IoT SIM card for a global cell network built for M2M data with easy activation, transparent pricing, and developer-friendly tools.

Orderable part numbers

GL1
GL1-10
GL1-100
GL1-1000

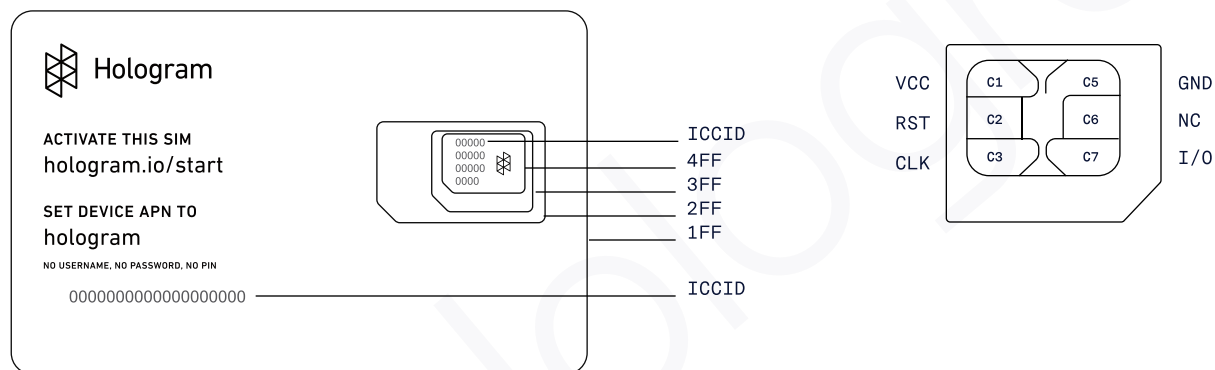
Past part numbers

SIM-E-TRI-GL
SIM-E-TRI-GL-10
SIM-E-TRI-GL-100
SIM-E-TRI-GL-1000

Network availability

Works globally with Hologram's 2G through LTE network where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

Mechanical specifications



Size

Form Factor	Size	Dimensions (mm)
1FF	Full-size	85.5 x 53.98 x 0.71
2FF	Mini-SIM	25 x 15 x 0.71
3FF	Micro-SIM	15 x 12 x 0.71
4FF	Mini-SIM	12.3 x 8.8 x 0.71

Pin Definitions

Pin	Signal	Description
C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware specifications

Environmental	Standard Grade	Industrial Grade
Temperature	-25-85°C	-40-105°C
Lifespan	25 years @ 25°C	15 years @ 85°C
Lifespan	100K read/write cycles	500K read/write cycles
Memory (NVM)	704KB	340KB
Memory (SRAM)	20KB	10KB

Electrical	Standard Grade	Industrial Grade
Operating Voltage	1.62V-5.5V	1.62V-5.5V

AC electrical parameters standards

ETSI 3GPP TS 102 221(UICC Terminal Interface Physical & Logical Characteristics)
 ETSI TS 102 671 v9.1.0(M2M Physical and Logical Characteristics)
 ISO 7816-3 standard for (Cards with Contacts - Electrical interface and transmission protoc

Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS	 GSMA	SGP11 RSP v3.1; SGP14 eUICC PKI v1.1; SGP02 v3.2 ; SGP05 eUICC PP-0089
	 simalliance	eUICC Profile Package v2.1
	 GLOBALPLATFORM®	Product Qualification
Production	 GSMA Security Accreditation Scheme	SAS-UP eUICC : EUM
Remote SIM provisioning	 GSMA	SGP01 RSP v1.1 ; SGP11 RSP v3.1 & 3.2; SGP14 eUICC PKI v1.1 ; SAS-SM

RoHS and REACH compliance

Hologram, Inc. hereby declares that the aforementioned Hologram products, placed on the European Community market by the Company and its subsidiaries is compliant with Directive 2011/65/EU on the Restriction of Certain Hazardous Substances in Electrical and Electronic Equipment.

More information: <https://www.samsung.com/semiconductor/about-us/global-compliance/>

Embedded form factor

MFF2, QFN8

Product overview

A secure IoT SIM card for a global cell network built for M2M data with easy activation, transparent pricing, and developer-friendly tools.

Orderable part numbers

GL1-MFF2
GL1-MFF2-250
GL1-MFF2-2500

Past part numbers

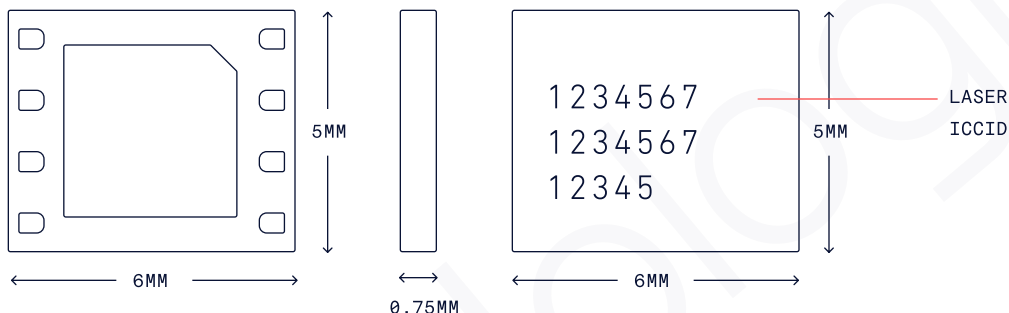
SIM-E-MFF2-GL
SIM-E-MFF2-GL-250
SIM-E-MFF2-GL-2500

Network availability

Works globally with Hologram's 2G through LTE network where coverage is available.
More information: <https://www.hologram.io/pricing/coverage>

Mechanical specifications

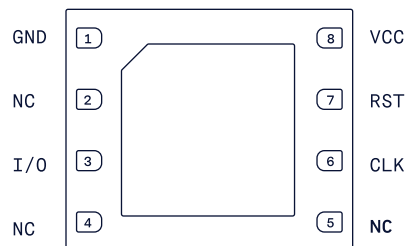
Bottom View



Pin Definitions

Pin	Signal	Description
1	GND	Ground
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

Top View



Size



Hardware specifications

Environmental	Standard Grade	Industrial Grade
Temperature	-25-85°C	-40-105°C
Lifespan	25 years @ 25°C	15 years @ 85°C
Lifespan	100K read/write cycles	500K read/write cycles
Memory (NVM)	704KB	340KB
Memory (SRAM)	20KB	10KB

Electrical	Standard Grade	Industrial Grade
Operating Voltage	1.62V-5.5V	1.62V-5.5V

AC electrical parameters standards

ETSI 3GPP TS 102 221(UICC Terminal Interface Physical & Logical Characteristics)
 ETSI TS 102 671 v9.1.0(M2M Physical and Logical Characteristics)
 ISO 7816-3 standard for (Cards with Contacts - Electrical interface and transmission protoc

Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS	 GSMA	SGP11 RSP v3.1; SGP14 eUICC PKI v1.1; SGP02 v3.2 ; SGP05 eUICC PP-0089
	 simalliance	eUICC Profile Package v2.1
	 GLOBALPLATFORM®	Product Qualification
Production	 GSMA Security Accreditation Scheme	SAS-UP eUICC : EUM
Remote SIM provisioning	 GSMA	SGP01 RSP v1.1 ; SGP11 RSP v3.1 & 3.2; SGP14 eUICC PKI v1.1 ; SAS-SM

RoHS and REACH compliance

Hologram, Inc. hereby declares that the aforementioned Hologram products, placed on the European Community market by the Company and its subsidiaries is compliant with Directive 2011/65/EU on the Restriction of Certain Hazardous Substances in Electrical and Electronic Equipment.

More information: <https://www.samsung.com/semiconductor/about-us/global-compliance/>

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Hologram:](#)

[GL1-MFF2-250](#) [GL1](#)